

## Kevin Turner

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### EXECUTIVE PROFILE

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High performing, strategic thinking, resourceful professional with 25 years' experience in electronics design, manufacturing, test and procurement with the last 10 years focused on innovating patentable world class and scalable Collaborative Solutions that included tools, Yield prediction, Process Characterization, Optimizing NPI launches, Product Transfers, deployment and implementations. Well experienced in project management from product development across 6 locations in 3 geographical continents, to deploying and certifying 24 sites globally to enable standardization and consistency of results. Analyzed existing solutions from newly acquired companies (eg Solectron), and merged their best parts into one globally standardized Best Practice process and toolset. Transitioned and centralized essential low-value activities from high to low cost regions for data collection, library generation and development of software solutions; while de-centralizing the core high value activities to be closer to the end customer, such as the Analysis, and direct collaboration with the Customer Design Teams.

Activities included the team setup and development (recruiting/staffing/training), budget management, analyzing and prioritizing customer requirements based on Value-Add, Road-mapping, defining project scope (cost, timelines, performance and requirement), enhancing customer experience, cost avoidance, continuous design improvements, risk management and conducting status meetings and customer reviews. My task was to provide XXX with a sustainable competitive advantage that enabled customers to achieve higher Value Add at lower costs, through the achievement of defined business, financial, and organizational objectives, via a complement of proactive, forward thinking, innovative and intuitive leadership expertise.

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### PROFESSIONAL EXPERIENCE

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⇒ **Company A**

**July 2006 - Present**

**Title: Sr. Director of Engineering Tools and Process**

1. Reporting to the SVP, provided XXX with a competitive advantage by conceptualizing and introducing world class Scalable Methodologies, Toolsets and Best Practice Process' for Analysis, that provided global standardization across 24+ sites. This Standardization provided consistent repeatable Analysis results based on XXX complexity, Design Technology, and Manufacturing Process.
2. Received two Patents for "Innovative System and Method Design for IC Chips". I have others pending in this space, plus have applied for an additional 3 Patents on "**Method and System for Automated Yield Processes**". Also received separate recognition from XXX for my contribution in 2011.
2. Achieved **Time-to-Market reduction** from 5 days to 2 or 1 day by streamlining and integrating an automated process within XXX, into the **Customers own design process**, thus enabling the Customer to **reduce Product costs, eliminate un-necessary design re-spins, and maximize production yields**. This was achieved through analysis at multiple iterations throughout the Design cycle, enabling earlier identification, classification, and quantification of valid issues/defects. Our aim was to eliminate ALL design re-spins as a result of Manufacturing, Test or Procurement related issues.
3. Defined Methodologies and Tools for quantifying "**Process R&D**" via "**Process Characterization Studies**" into "**Design Guidelines**". This enabled us to reduce from 1 year to 3 months new releases of "**Design and Manufacturing Guidelines**" that would be automatically and simultaneously embedded within ALL, Design and Yield Prediction toolsets worldwide. This required an architectural approach to Content that enabled us to enhance the breadth and depth of Design Rules by **Product Technology and Manufacturing Process**
4. Provided guidance to Corporate IT on XXX and AML Cleansing, XXX Reconciliation between Schematic, Layout, Procurement and Manufacturing. Also how to leverage Tools and Process into NPI Activities to shorten via Automation the process of NPI Setups, Product Transfers, improve consistency and repeatability for new Product Launches.
5. Managed and completed successfully within **budget, scope and cost**, multiple (8 to 10 projects simultaneously) Design, and Manufacturing related applications which included preparing **Project charter, ROI calculation, Change management and Risk mitigations**.
6. Embedded the XXX Analysis Process within the XXX Product Life Cycle (**FPLC**), which supported me in managing the **deployment, training, implementation and certification** of hundreds of XXX Engineers across multiple XXX Center of Excellences (COE) for XXX worldwide, which included Asia, Western and Eastern Europe, North and South America.

7. Broadened the XXX Analysis Services to include PCB and Sheetmetal Fabrication, PCB and Product Assembly and Test, Tolerance Stack-up Analysis, Fixture Stress Analysis, XXX and AML Cleansing. Architected the integration of several of these services into the **one environment**, to bring significant Customer value and enabling us to increase **Service penetration by approximately 30%**.
8. Built and managed a regional ECAD Library and PCB design team in Malaysia to support XXX Design and XXX team. The team consists of 30 people including engineers and managers, providing **annualized savings of \$10M**.
9. Defined and Implemented Service Level Agreements (**SLA**) and Quality Management System (**QMS**) for the Component and Library teams that increase efficiency, accelerated delivery and reduced field return. This also helped to identify and leverage the **Best Practices** across the various sites, and drove a method of **Continuous Improvement** that supported **Standardization across the Sites**.

⇒ **Company A Technology Leadership Group,**

**Jan 2001 - July 2006**

**Title: Director of Engineering Design Services**

1. Reporting to the CTO, I was Business Responsible and Global Program Manager for a Design and Manufacturing Collaboration Program
2. XXX Technical and Business representative along with Cadence Design Systems Inc. and Hewlett-Packard Co. to establish SpinCircuit Inc., an e-commerce company. SpinCircuit was an Internet gateway that would link printed circuit board (PCB) design engineers directly to suppliers of more than two million parts through its online catalog.
3. **Steering Committee Team member** of the XXX Global Best Practices, with a strong focus on leveraging Design, Procurement, NPI, Manufacturing and Test.
4. Contract Negotiations involving Strategic Alliances and deals worth several \$M
5. Managed a globally dispersed team of 30+ Technical Experts, Software Development, Application Trainers and Technical Content Creators. Built and setup the Component Engineering teams in China, Malaysia, and Mexico. In addition, built XXX Teams in 34 location worldwide, across 23 countries
6. Responsible for gathering **Customers Requirements**, prioritizing and developing these into Technical Solutions. Also established Product Requirements for streamlining the Design to Manufacturing process, via cross-functional teams from Design, Procurement, Design Engineers, Process Engineer, Fabrication group, Project manager and XXX Engineers.
7. Responsible for the evaluation of Software solutions from external vendors and in **determining "Buy" versus "In-house Development" Solutions**. Factors such as IP, integration to Internal Systems and providing significant competitive advantage would favor In House development compared to significant customization of a "Buy off the Shelf" Product.
8. Initiator of the XXX Project Development team for an integrated XXX Program with a "Design and Manufacturing Collaboration" Initiative.
9. Managed the development and released of several automation tools around Component requests, Library creation and Component Data collection,

⇒ **Company A**

**April 2000 – Jan 2001**

**Title: Regional Design Center Director**

1. Responsible for the Operation of the Irish and UK Design Centers.
2. Managed Design for Digitally complex Mass Storage Servers Controllers Cards and RF Design
3. Responsible for both the Design, NPI of Products designed in the UK and Ireland, plus then Product Transfer to China, Czech Republic and Mexico of the same Products.
4. Introduced a Standard approach to XXX Analysis, and Improved XXX Reporting format.
5. Initiated within the company an awareness of the need to standardized and publish Design Rules.

⇒ **Company B**

**May 1998 – April 2000**

**Title: Design Center Manager and Corporate Staff Engineer**

1. Reporting into the European President, I was responsible for the Irish Design Centre plus Special Projects for Corporate.
  - a. Special Projects involved leveraging various technologies across the XXX to bring Technical Solutions to complex customer problems
    - i. DII Group owned a series of Electronics related companies, such as XXX Contract Manufacturing, Multek PCB Fabricator, Orbit Semiconductors, IRI Stencil Manufacturers, TTI Testron Test Development and Fixture Generation, Chemtech PCB Routing
    - ii. Creating a Video animation for Investors to demonstrate this **Vertical Integration**
2. Initiated a Joint Venture between Cadence and DII Group on Design and Manufacturing opportunities to provide Product reduction costs through miniaturization for existing Customer Projects.

3. Responsible for both the Design and the NPI of all Products that were designed within the Design Center
4. Wrote a Paper on the theory of XXX and YYY testing, which was later presented to Qualmark and the University of Maryland for evaluation of an alternative method of estimating Product Life.
5. Wrote several Papers for Future Circuits and Future EMS Publications

⇒ **Company C**

**July 1995 – April 2000**

**Title: Test /Debug Engineering Manager & Corporate Staff Engineer**

1. Reporting into the Plant Manager, I was responsible for the Irish Test and Debug & Troubleshoot Departments plus Special Projects for Corporate
2. Direct Manager of 30 Engineers and Debug Technicians
3. Drove a reduction of PCB backlog from 15% of Volume to 0.3% during a volume increase of 300% over a 12 month period
4. Introduced a Product Debug Tracking System plus a SMART Card approach to assist in the rapid detection of Defects and Process faults.
5. Introduced SPC Controls on Manufacturing Process
6. Explored new concepts of Defect Diagnostics through AOI, X-Ray, and Thermal Analysis
7. Introduced Production Process in a new Start-up via acquisition of Czech Republic.
8. Responsible for driving Plant Quality in the Czech Republic facility and for achieving IPC 9001 standards for the site.

⇒ **Company D**

**May 1992 – July 1995**

**Title: Vendor Engineering Manager**

1. Local sourcing of vendors for Components and Assemblies from US, Germany and Japanese Vendors
2. Responsible for the Out-Sourcing of PCB Manufacturing to Puerto Rico, and again to DoVatron for both Low Volume High Mix and High Volume low mix range of Products.
3. Responsible for the outsourcing of Glass Manufacturing via employee local Start up

⇒ **Company E**

**Sept 1988 – May 1992**

**Title: PCB and Glass Manufacturing and Test Manager**

1. Responsible for the PCB Test, Manufacturing and Glass Manufacturing departments
2. Introduced Kan-Ban System & reduce WIP to less than 4 Hours of Buffer

⇒ **Company F**

**Feb 1985 – Sept 1988**

**Title: ICT Software Programmer / Test Development Engineer**

1. Responsible for In-Circuit Test Development and Test Process Management
2. Introduced the concepts of Cluster testing on ICT Platforms, in conjunction with ICT Platform vendors

⇒ **Company F**

**Sept 1982 – Feb 1985**

**Title: Debug Technician**

1. Debug of Production & Field Returns of Electronics & Electro Mechanical Products

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**SKILLS**

1. Leadership and Collaborative Management skills in a Global culturally diversified Environment for > 10 years
2. Excel at Leveraging, Integrating and Simplifying Business Use Cases to eliminate Waste, drive Productivity and efficiency
3. Willing to Travel extensively. Lived in Malaysia for several years.
4. Road mapping and prioritizing multiple projects based on both Business requirements and Foundation building
5. Project Management, Value Stream Mapping, Root Cause Analysis, SixSigma, Lean Manufacturing, Waste Elimination.
6. Excel, Word, Powerpoint, MS Visio, MS Project, Outlook, Valor Trilogy, Boothroyd & Dewhurst, Cadence Allegro, Concept, Orcad, PE Librarian, Autoplace and Autoroute, SPC, Excel VBA.

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**EDUCATIONAL QUALIFICATION**

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|---|------------------------------------------------------------|---------------------|
| ⇒ | <b>Irish Management Institute</b>                          | <b>199Xto 19XX</b>  |
|   | 1. BA (Bachelor of Arts) (Grade 1 in 2nd Class Honors)     |                     |
| ⇒ | <b>Regional Technical College Dundalk</b>                  | <b>19XX to 19XX</b> |
|   | 2. National Diploma in Electrical Engineering (Credit)     |                     |
| ⇒ | <b>Regional Technical College Sligo</b>                    | <b>19XX to 19XX</b> |
|   | 3. National Certificate in Electrical Engineering (Credit) |                     |

⇒ Available upon request